

U.S. Patent Application Serial No. 10/612,990
Response filed March 8, 2005
Reply to OA dated December 15, 2004

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A multilayer circuit board, comprising:
a plurality of cable layers, each of which includes electric conductive sections;
a plurality of first insulating layers, each of which encloses said electric conductive sections
in each cable layer and fills spaces between said electric conductive sections; and
post vias electrically connecting said electric conductive sections in one cable layer to those
in another cable layer,
wherein height of said electric conductive sections in each cable layer are regulated by
abrading to be equal to that of said first insulating layer enclosing those electric conductive sections.

Claim 2 (Currently Amended): The multilayer circuit board according to claim 1, further
comprising a second insulating layer, which is formed to enclose said post vias,
wherein height of said post vias are regulated by abrading to be equal to that of said second
insulating layer.

Claims 3 - 10 (Canceled)